imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Laird TECHNOLOGIES

Innovative **Technology** for a **Connected** World

Laird

Tflex[™] 300 Series Thermal Gap Filler

UNIQUE SILICONE GEL OFFERS COMPLIANCY, THERMAL RESISTANCE

Tflex[™] 300, at pressures of 50psi, will deflect to over 50% the original thickness. This high rate of compliancy allows the material to "totally blanket" the component, enhancing thermal transfer. The material has a very low compression set enabling the pad to be reused many times.

Tflex[™] 300, in achieving its stellar compliancy, does not sacrifice thermal performance. With a thermal conductivity of 1.2 W/mK, low thermal resistances can be achieved at low pressures.

Tflex[™] 300-H is offered with a hard, metallized liner option for easy handling and improved rework. The metallized liner's lower coefficient of friction also allows for easy assembly of parts that must slide together, such as a card into a chassis.

Tflex[™] 300-TG is offered with a cut-through resistant Tgard[™] silicone liner. The TG liner offers a guaranteed dielectric barrier, and easier part handling for mass production.

FEATURES AND BENEFITS

- Extreme compliancy allows material to "totally blanket" component(s)
- Thermal conductivity of 1.2 W/mK
- Available in thicknesses from 0.020" 0.200" (.5mm 5.0mm)
- Low compression set enables the pad to be reused many times

APPLICATIONS

- Notebook and desktop computers
- Telecommunication hardware
- Flat panel displays
- Memory modules
- Power conversion equipment
- Set top box
- Lighting ballast
- Automotive electronics
- LED lighting
- Handheld electronics
- Optical disk drives
- Vibration dampening

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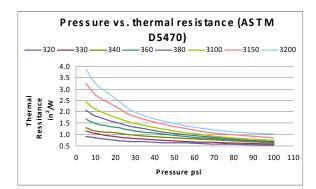


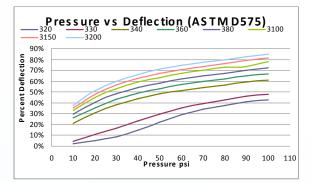
Innovative **Technology** for a **Connected** World

Tflex[™] 300 Series Thermal Gap Filler

TFLEX™ 300 TYPICAL PROPERTIES

	TFLEX [™] 300	TEST METHOD
Construction	Filled silicone elastomer	NA
Color	Light green	Visual
Thermal Conductivity	1.2 W/mK	ASTM D5470
Hardness (Shore 00)	27 (at 3 second delay)	ASTM D2240
Density	1.78 g/cc	Helium Pyncometer
Thickness Range	0.020"200" (0.5 - 5.0mm)*	
Thickness Tolerance	±10%	
UL Flammability Rating	94 V0	UL
Temperature Range	-40°C to 160°C	NA
Volume Resistivity	10 ^13 ohm-cm	ASTEM D257
Outgassing TML	0.56%	ASTM E595
Outgassing CVCM	0.10%	ASTM E595
Coefficient Thermal Expansion (CTE)	600 ppm/C	IPC-TM-650 2.4.24





STANDARD THICKNESSES

0.020 to 0.200-inch (0.5 to 5.0mm)*

0.020 to 0.200-inch thick material available in 0.010-inch (0.25mm) increments

0.250-inch (6.4 mm) also available with TG liner option only.

*Inquire about availability of material and options above 0.200-inches

OPTIONS

Tgard[™] "TG" dielectric barrier available to aid in handling and PET dielectric "H" liner available for applications where easy slide assembly is desirable

MATERIAL NAME AND THICKNESS

Tflex[™] indicates elastomeric gap filler product line 3xxx indicates high recovery '3 series' 1.2 W/mK material -DC1 designates proprietary tack eliminated coating -TG indicates Tgard[™] liner option -H indicates hard PET liner option

EXAMPLES

Tflex[™] 3120 = standard 0.120-inch thick Tflex[™] 300 material Tflex[™] 3120DC1 = 0.120-inch thick material with DC1 coating Tflex[™] 3120TG = 0.120-inch thick material with Tgard[™] liner Tflex[™] 3120H = 0.120-inch thick material with hard PET liner

THR-DS-TFLEX-300 1010

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